



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

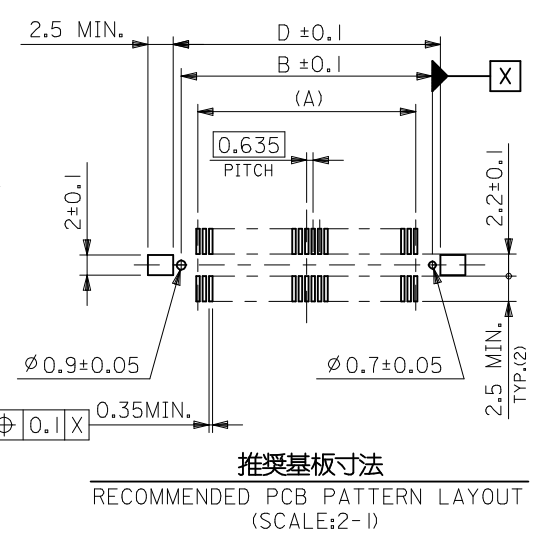
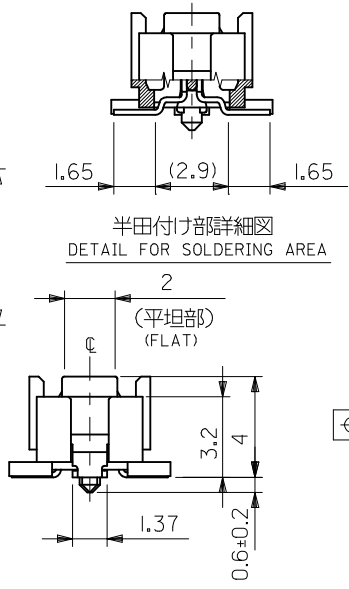
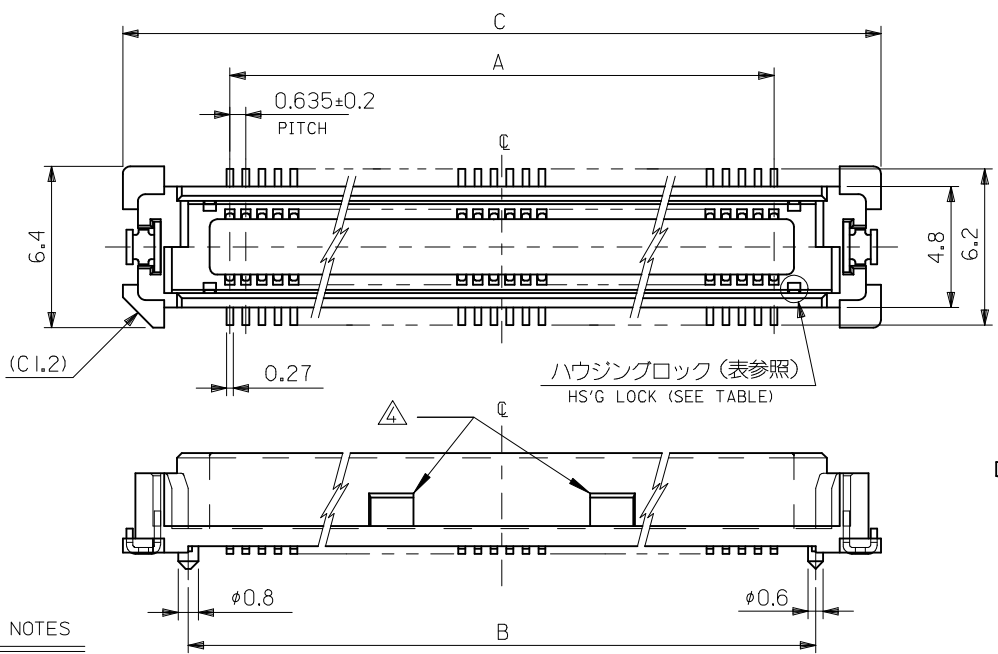
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



10 9 8 7 6 5 4 3 2 1



注記 NOTES

- 材質 MATERIAL
 ハウジング : ガラス入り LCP、白色、UL94V-0
 HOUSING: G.F.LCP, WHITE, UL94V-0
 ターミナル : 銅合金 (t=0.2)
 TERMINAL: COPPER ALLOY
 ネイル : 銅合金 (t=0.25)
 NAIL: COPPER ALLOY
- メッキ仕様 PLATING
 ターミナル : 接点部 : 金メッキ 0.25 μm MIN.
 TERMINAL : CONTACT AREA; GOLD 0.25 MICROMETER MIN.
 半田付け部 : 錫メッキ 2.0 μm MIN.
 SOLDER TAIL AREA; TIN 2.0 MICROMETER MIN.
 下地メッキ : ニッケルメッキ 2.0 μm MIN.
 UNDER-PLATING: NICKEL 2.0 MICROMETER MIN.
 補強金具 : 錫メッキ 1.0 μm MIN.
 FITTING NAIL : TIN 1.0 MICROMETER MINIMUM
 下地メッキ : ニッケルメッキ 1.0 μm MIN.
 UNDER-PLATING: NICKEL 1.0 MICROMETER MIN.

10 mm	53553 SERIES
9 mm	53552 SERIES
8 mm	53551 SERIES
7 mm	53481 SERIES
6 mm	53467 SERIES
5 mm	53475 SERIES
基板間寸法 STACKING HEIGHT	嵌合相手 TO BE MATED WITH

WITHOUT HSG LOCK	80.47	84.07	78.87	75.565	—	52760-2479	240
	67.77	71.37	66.17	62.865	—	52760-2079	200
	61.42	65.02	59.82	56.515	—	52760-1879	180
	55.07	58.67	53.47	50.165	—	52760-1679	160
	48.72	52.32	47.12	43.815	—	52760-1479	140
	42.37	45.97	40.77	37.465	—	52760-1279	120
	36.02	39.62	34.42	31.115	—	52760-1079	100
	32.85	36.45	31.25	27.94	—	52760-0979	90
	29.67	33.27	28.07	24.765	52760-0878	—	80
	23.32	26.92	21.72	18.415	52760-0678	52760-0679	60
WITH HSG LOCK	20.15	23.75	18.55	15.24	52760-0578	52760-0579	50
	13.80	17.40	12.20	8.89	52760-0378	52760-0379	30
	10.62	14.22	9.02	5.715	—	52760-0279	20
D	C	B	A	EMBOSSED TAPE PACKAGE オーダー番号 ORDER NO.	STICK PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS	

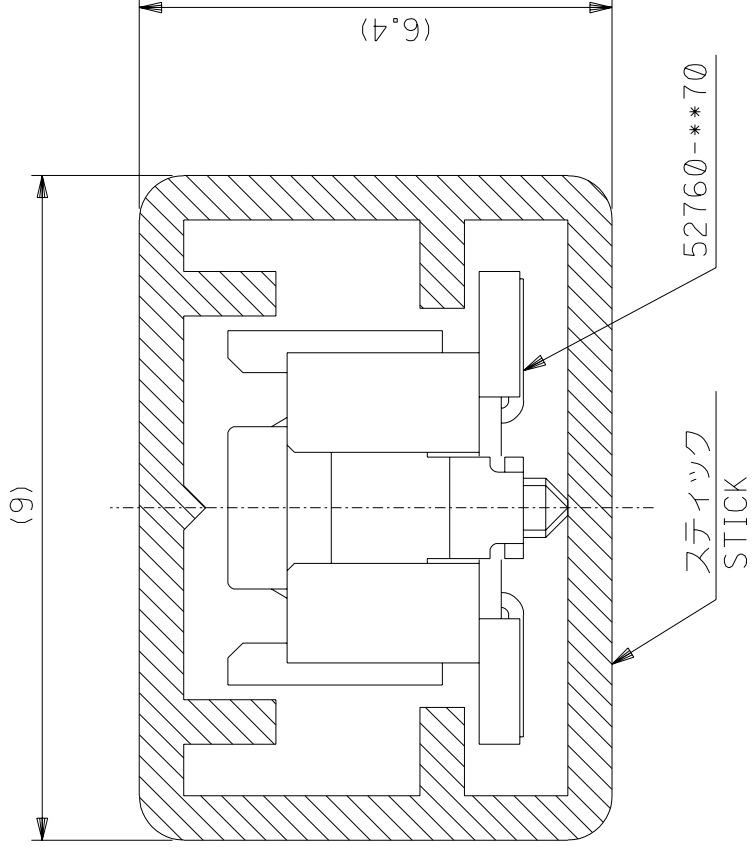
- 200極以下のテール平坦度は 0.1 MAX.、
 TAIL COPLANARITY TO BE 0.1 MAX.
 240極のテール平坦度は 0.12 MAX.とする。
 IN 240 CIRCUITS, TAIL COPLANARITY TO BE 0.12 MAX.

△ 本製品は 2016 年 6 月 30日まで形状変更期間中となります。
 THIS PRODUCT IS DURING A FORM CHANGE PERIOD TILL JUNE 30, 2016.
 その為、図示形状が無い場合もございますが、製品機械性能上問題ございません。
 THEREFORE, THERE MAY NOT BE THE ILLUSTRATED SHAPE.
 HOWEVER, IT DOSE NOT AFFECT ON CONNECTOR MECHANICAL PERFORMANCE.

REVISED EC NO: J2016-0873 DRWN: SASAYAMA 2016/02/22 CHKD: TAKEUCHI 2016/02/25 APP: KMORIKAWA 2016/02/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY Y. WADA	DATE '04/02/26	TITLE 0.635 PITCH B-T0-B S/T REC. HSG ASSY -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY M. SASAO	DATE '04/02/26	molex	
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M. SASAO	DATE '04/02/26		
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.	DOCUMENT NO.	SD-52760-013	
10 OVER	30 UNDER	±0.25	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SHEET NO. 1 OF 1		

9 8 7 6 5 4 3 2 1

DWG. NO. SD-52760-015



注)
NOTES.

1. スティック両端はキャップ止め。
BOTH ENDS WITH CAPS.
2. 全長: 6.00 ± 2
TOTAL LENGTH
3. 肉厚: 0.6 ± 0.2
THICKNESS
4. 量産対応済の極数については、
SD-52760-013 を参照下さい。
SEE SD-52760-013 FOR AVAILABLE ITEMS.
5. 本製品は52760-015の鉛フリー品
である。
THIS PRODUCT IS LEAD FREE OF 52760-015.

DIMENSIONS IN METRIC DO NOT SCALE DRAWING

角度	ANGLE	$\pm 3^\circ$
以上 30 OVER		± 0.3
以上 10 OVER	未満 30 UNDER	± 0.25
未満 10 UNDER		± 0.2
一般公差 GENERAL TOLERANCES		

MODEL NO. 52760-015

材料 MATERIAL	スティック: ポリ塩化ビニル STICK: P.V.C	
仕上げ FINISH	—#—	
適用電線範囲 WIRE RANGE	—#—	
被覆外径 INS. RANGE	—#—	
DRAWN BY '04/02/26	CHK'D BY '04/02/26	
Y.W.	M.S.	M.SASAO
DR.	DATE	SCALE
新規作成 RELEASED (J2004-2690)	変更内容 REVISION RECORD	尺度 SCALE
Y.W.	M.S.	—#—
DR.	DATE	SCALE

材料
MATERIAL
スティック: ポリ塩化ビニル
STICK: P.V.C

仕上げ
FINISH
—#—

適用電線範囲
WIRE RANGE
—#—

被覆外径
INS. RANGE
—#—

DRAWN BY '04/02/26
CHK'D BY '04/02/26

Y.W. M.S. M.SASAO
DR. DATE SCALE

材料
MATERIAL

スティック: ポリ塩化ビニル
STICK: P.V.C

仕上げ
FINISH

適用電線範囲
WIRE RANGE

被覆外径
INS. RANGE

DRAWN BY '04/02/26
CHK'D BY '04/02/26

Y.W. M.S. M.SASAO
DR. DATE SCALE

材料
MATERIAL
スティック: ポリ塩化ビニル
STICK: P.V.C

仕上げ
FINISH
—#—

適用電線範囲
WIRE RANGE
—#—

被覆外径
INS. RANGE
—#—

DRAWN BY '04/02/26
CHK'D BY '04/02/26

Y.W. M.S. M.SASAO
DR. DATE SCALE

6	52760-2479	240
7	-2079	200
8	-1879	180
9	-1679	160
10	-1479	140
12	-1279	120
14	-1079	100
15	-0979	90
17	-0879	80
18	-0779	70
19	-6879	68
21	-0679	60
23	-0579	50
27	-0479	40
32	-0379	30
39	52760-0279	20
梱包数 QUANTITY	MATERIAL NO.	極数 NO. OF CKT.

MOLEX-JAPAN CO.,LTD.
日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称
52760-015
STICK PACKAGING
-LEAD FREE-

DWG. NO. SD-52760-015
REV 0